

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5721627

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	TAKANORI OMICHI	09/04/2019
RECEIVING PARTY DATA		
Name:	SANSHA ELECTRIC MANUFACTURING COMPANY, LIMITED	
Street Address:	1-56, NISHIAWAJI 3-CHOME, HIGASHIYODOGAWA-KU	
City:	OSAKA-SHI, OSAKA-FU	
State/Country:	JAPAN	
Postal Code:	533-0031	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	29705573
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	D3301-00241	
NAME OF SUBMITTER:	JOSEPH A. POWERS	
SIGNATURE:	/Joseph A. Powers/	
DATE SIGNED:	09/17/2019	
Total Attachments: 2		
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ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, Takanori Omichi of Osaka-shi, Osaka-fu, Japan

Hereby sell, assign and transfer to Sansha Electric Manufacturing Company, Limited, a corporation of Japan, having a place of business at 1-56, Nishiawaji 3-chome, Higashiyodogawa-ku, Osaka-shi, Osaka-fu, Japan, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled

SEMICONDUCTOR MODULE

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements, and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal

representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

The undersigned declare further that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of this assignment, patent or patent application and any patent issuing thereon.

Date : September 4, 2019

OMICHI TAKANORI

OMICHI Takanori